



- CDMA 450 F-Band RF SAW Filter
- 3.8 x 3.8 x 1.4 mm Surface-mount Package
- Complies with Directive 2002/95/EC (RoHS)

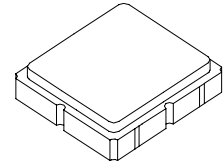


SF1215D

423.75 MHz SAW Filter

Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+30	dBm
Maximum DC Voltage between any Two Terminals	30	VDC
Storage Temperature Range	-40 to +85	°C
Suitable for Lead-free Soldering - Maximum Soldering Profile	260°C for 30 s	



SM3838-6

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Nominal 1 dB Center Frequency	f_c	1		423.75		MHz
Passband Insertion Loss	IL			2.7	3.5	dB
VSWR				1.5:1	2:1	
Rejection		1, 2, 3				dB
0.3 to 411.6 MHz			40	48		
411.6 to 415.9 MHz			35	47		
442.0 to 600.0 MHz			40	47		
600.0 to 1200 MHz			30	40		
1200 to 2000 MHz			20	35		
Operating Temperature Range	T_A	1	-30		+80	°C
Impedance at f_c Source, single ended			50 ohm			
Load, single ended			50 ohm			

Case Style	SM3838-6 3.8 x 3.8 mm Nominal Footprint	
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	644, YWWS	
Standard Reel Quantity Reel Size 7 Inch	1000 Pieces/Reel	
Reel Size 13 Inch	3000 Pieces/Reel	

Electrical Connections

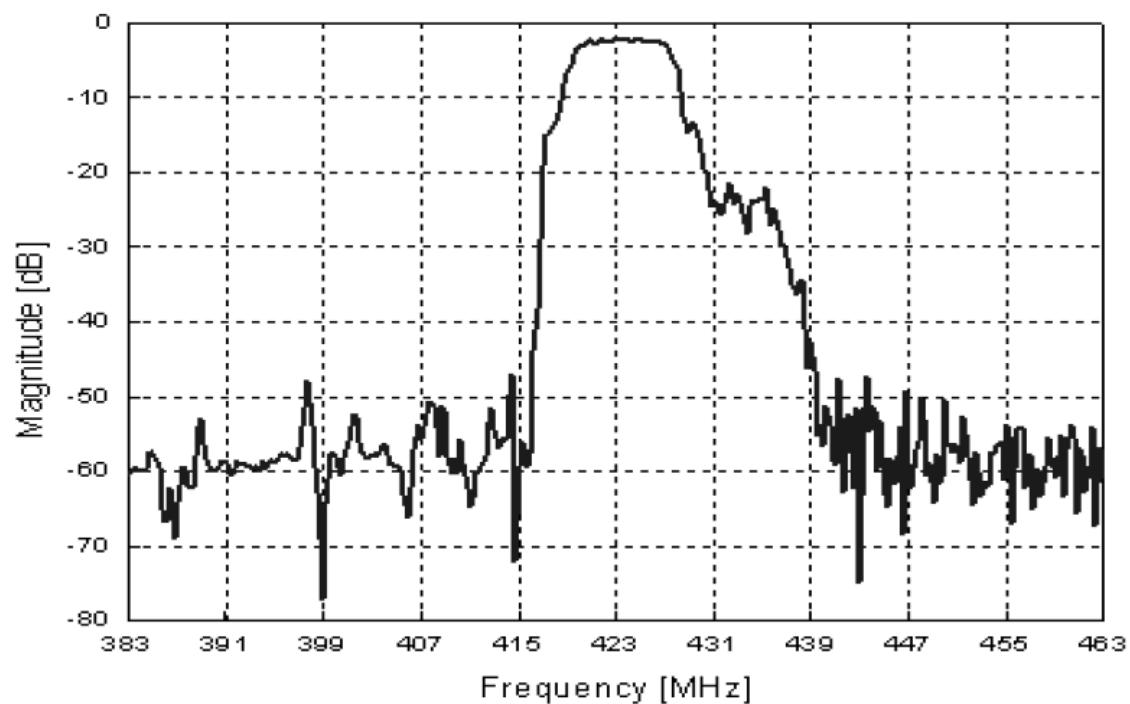
Connection	Terminals
Port 1	2
Port 2	5
Case Ground	All others



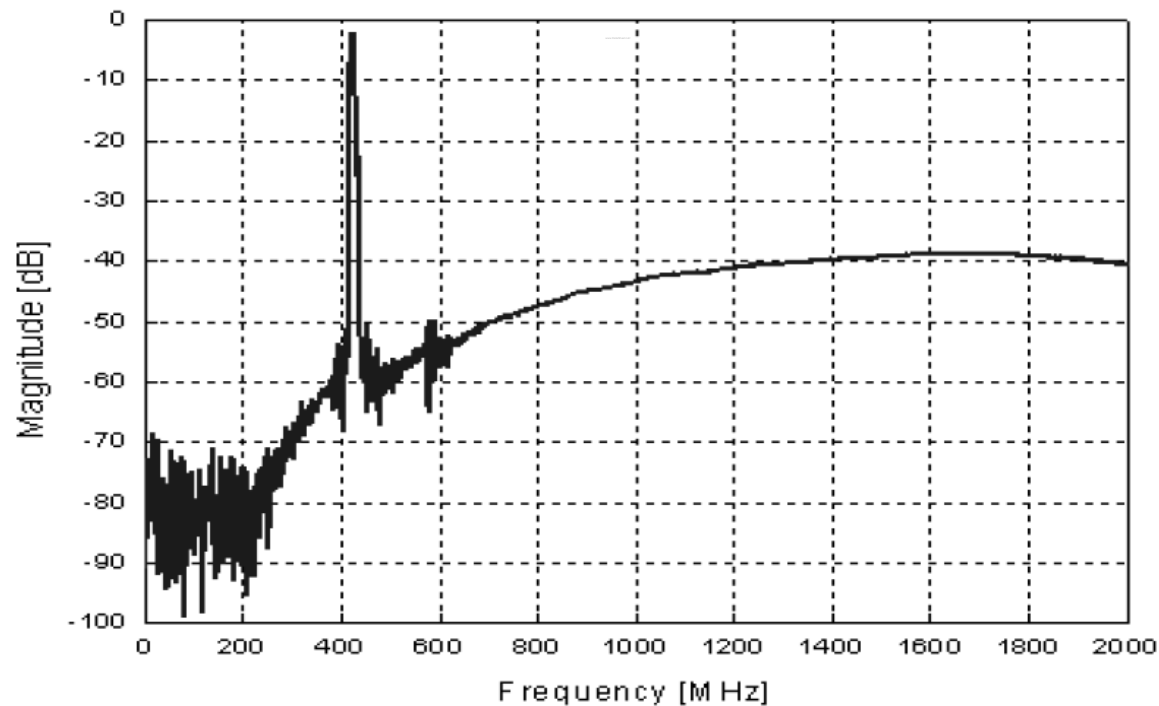
CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

Notes:

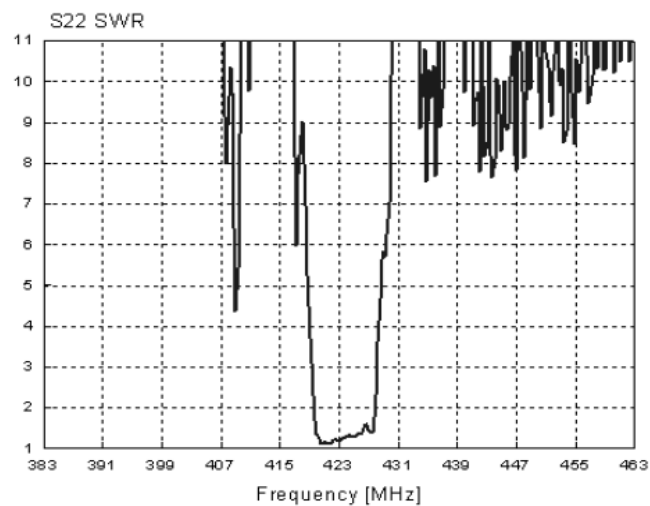
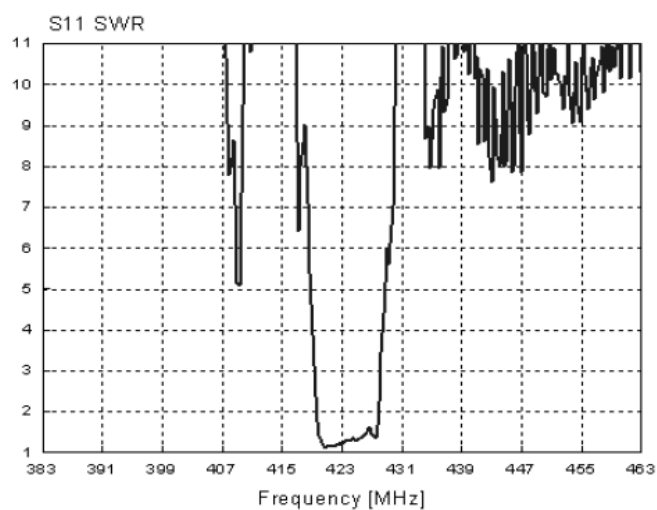
1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, f_c .
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."
5. The design, manufacturing process, and specifications of this filter are subject to change.
6. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
7. US and international patents may apply.
8. RFM, stylized RFM logo, and RF Monolithics, Inc. are registered trademarks of RF Monolithics, Inc.



Passband Plot



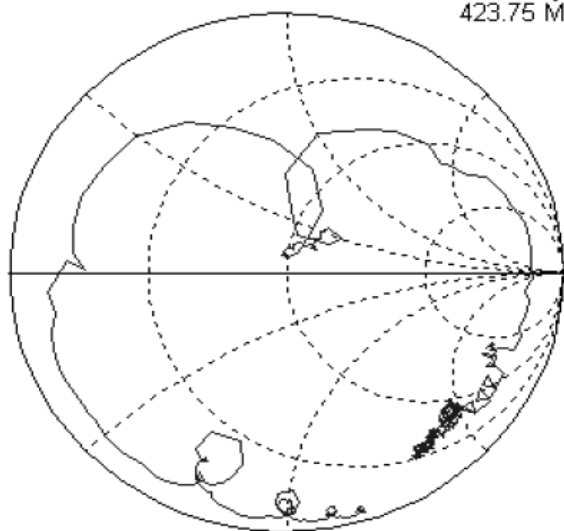
Wideband Plot



VSWR

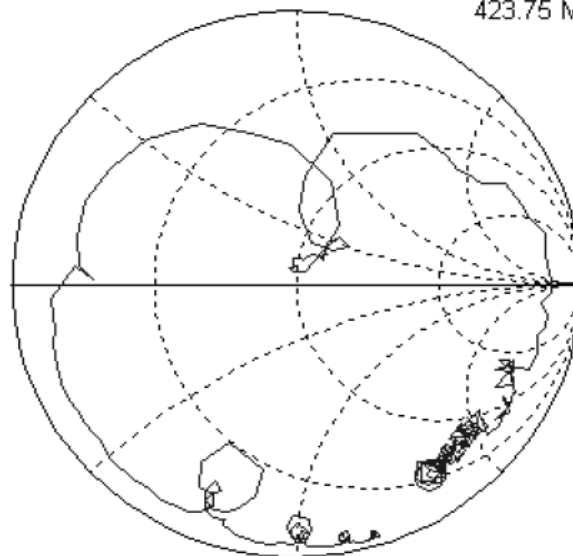
S11

$54.1556 + j12.5068$
423.75 MHz



S22

$53.2483 + j10.7862$
423.75 MHz



S11 and S22 Plots

Technical drawing of a circular component, likely a flange or end plate, showing three views: a top view, a side view, and a detail view.

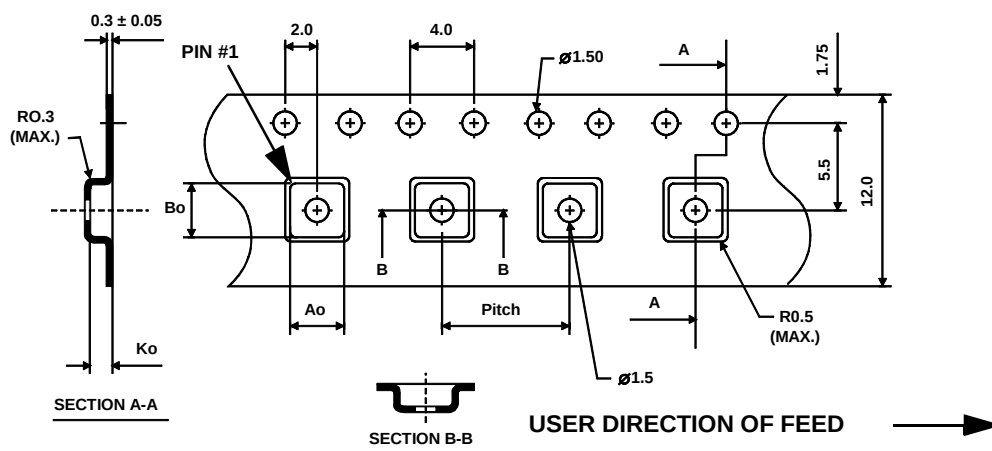
Top View: A large circle with a smaller concentric circle in the center. A horizontal dashed line and a vertical dashed line intersect at the center. A small circle with a crosshair is located at the center of the inner circle. An arrow points from the text "See Detail 'A'" to this central feature.

Side View: Two vertical lines representing the thickness of the component. The total thickness is labeled "12.0". The distance from the centerline to the outer edge is labeled "100 REF." and "B" REF.".

Detail View (A): A cross-sectional view of the central feature. It shows a circular hole with a diameter of 13.0. The hole is surrounded by a ring with a thickness of 2.0. The outer diameter of the ring is 20.2.

“B “ Nominal Size		Quantity Per Reel
Inches	millimeters	
7	178	1000
13	330	3000

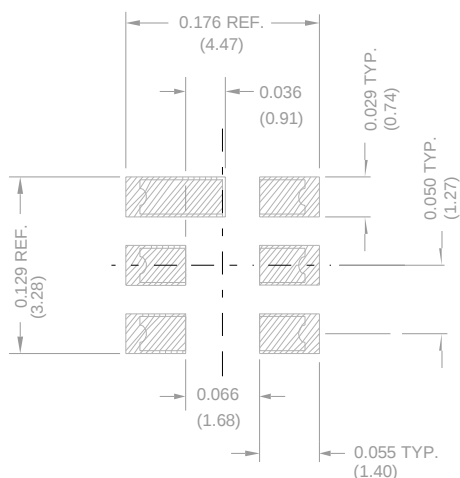
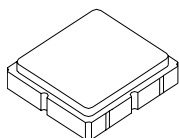
Carrier Tape Dimensions	
Ao	4.25 mm
Bo	4.25 mm
Ko	1.30 mm
Pitch	8.0 mm
W	12.0 mm



SM3838-6 Case

6-Terminal Ceramic Surface-Mount Case

3.8 X 3.8 mm Nominal Footprint



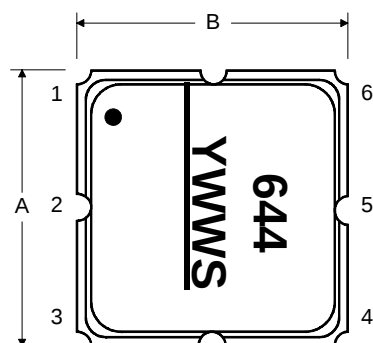
PCB Footprint

Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	3.60	3.80	4.0	0.14	0.15	0.16
B	3.60	3.80	4.0	0.14	0.15	0.16
C	1.30	1.50	1.70	0.05	0.06	0.067
D	0.95	1.10	1.25	0.037	0.043	0.05
E	2.39	2.54	2.69	0.090	0.10	0.110
G	0.90	1.0	1.10	0.035	0.04	0.043
H	1.90	2.0	2.10	0.75	0.08	0.83
I	0.50	0.6	0.70	0.020	0.024	0.028
J	1.70	1.8	1.90	0.067	0.07	0.075

Electrical Connections		
Connection		Terminals
Port 1	Single Ended Input	2
Port 2	Single Ended Output	5
	Ground	All others
Single Ended Operation Only		
Dot indicates Pin 1		

Materials	
Solder Pad Termination	Au plating 30 - 60 μinches (76.2-152 μm) over 80-200 μinches (203-508 μm) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 μinches Thick
Body	Al ₂ O ₃ Ceramic
Pb Free	

TOP VIEW



BOTTOM VIEW

